

IC

Reverse **Costing** & **Technology** Analysis



MEMS

SYSTEM

POWER

REPORT

STMicroelectronics LSM6DS3 6-Axis MEMS IMU

ST's extra small (only 6mm³) and sub-mA IMU named 2014 MEMS device of the year 50% footprint reduction, many process & design innovations



Combo sensors, and particularly 6-axis IMU, will represent the majority of the inertial MEMS market in the coming years according to Yole. This large adoption has not profited much to STMicroelectronics so far, but their latest innovation in the field could be a game changer. Indeed, the LSM6DS3 has been named "MEMS sensor device of the Year" in 2014 and ST had a big design win with a 6-axis IMU in the Apple Watch this year. Targeting the promising market of wearable, ST has done things right to be competitive in here...

By achieving 50% footprint reduction and decreasing considerably the power consumption compared to ST's previous generation IMU, the LSM6DS3 is ready to attack the mobile market where the competition on price is stronger than ever. In order to obtain this size of only 2.5x3x0.85mm, STMicroelectronics introduced many new features to its device. Indeed, the classical LGA 2-layer PCB has been replaced by an uncommon 3-layers PCB, the MEMS gyro and accelerometer have also been redesigned to be able to shrink the die size. On the processes side, new techniques borrowed from competitors products has been introduced in the MEMS fabrication and also a whole new process for the ASIC is now used allowing to embed 8KB of FIFO memory.

The LSM6DS3 is targeted for battery-powered smart sensor systems to be embedded in mobile and wearable devices and innovative objects for the Internet of Things (IoT).

The report includes a detailed technology and cost comparison with ST's previous generation LSM6DS0 and with leading edge 6-Axis IMUs from Bosch Sensortec (BMI160) and InvenSense (MPU-6500).





Title: MEMS IMU Pages: 140 Date: June 2015 Format: pdf + xls

PRICF: Full report: EUR 2,990 Technology report: EUR 1,990

COMPLETE TEARDOWN WITH:

- Detailed Photos
- Precise Measurements
- Material Analysis
- Manufacturing Process Flow
- Supply Chain Evaluation
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Véronique is in charge of structure analysis of semiconductors. She has a deep knowledge in chemical & physical technical analyses. She previously worked for 20 years in Atmel Nantes Laboratory.

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simulation Cost tool to evaluate the cost of any **MEMS** process or device:

From single chip to complex structures.

MEMS CoSim+ is a processbased costing tool used to evaluate the manufacturing cost per wafer using your own inputs or using the predefined parameters included in the tool.

It is possible to enter any MEMS process flow.



RELATED REPORTS

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** Technology Analysis report contains only Physical Analysis & Manufacturing Process Flow

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